

ABSTRACT OF THE DISCLOSURE

A packaging assembly includes a substrate; chip-site  
lands disposed on the first surface; first solder balls  
5 connected to the chip-site lands; second solder balls  
connected to the first solder balls including solder  
materials having higher melting temperatures than the  
first solder balls; a semiconductor chip having a plurality  
of bonding pads connected to the second solder balls on  
10 a surface of the semiconductor chip; and an underfill resin  
disposed around the first and second solder balls.